

**南亞電路板股份有限公司**

**NAN YA PRINTED CIRCUIT BOARD CORPORATION**

# **COMPANY BRIEFING**

**January 2010**

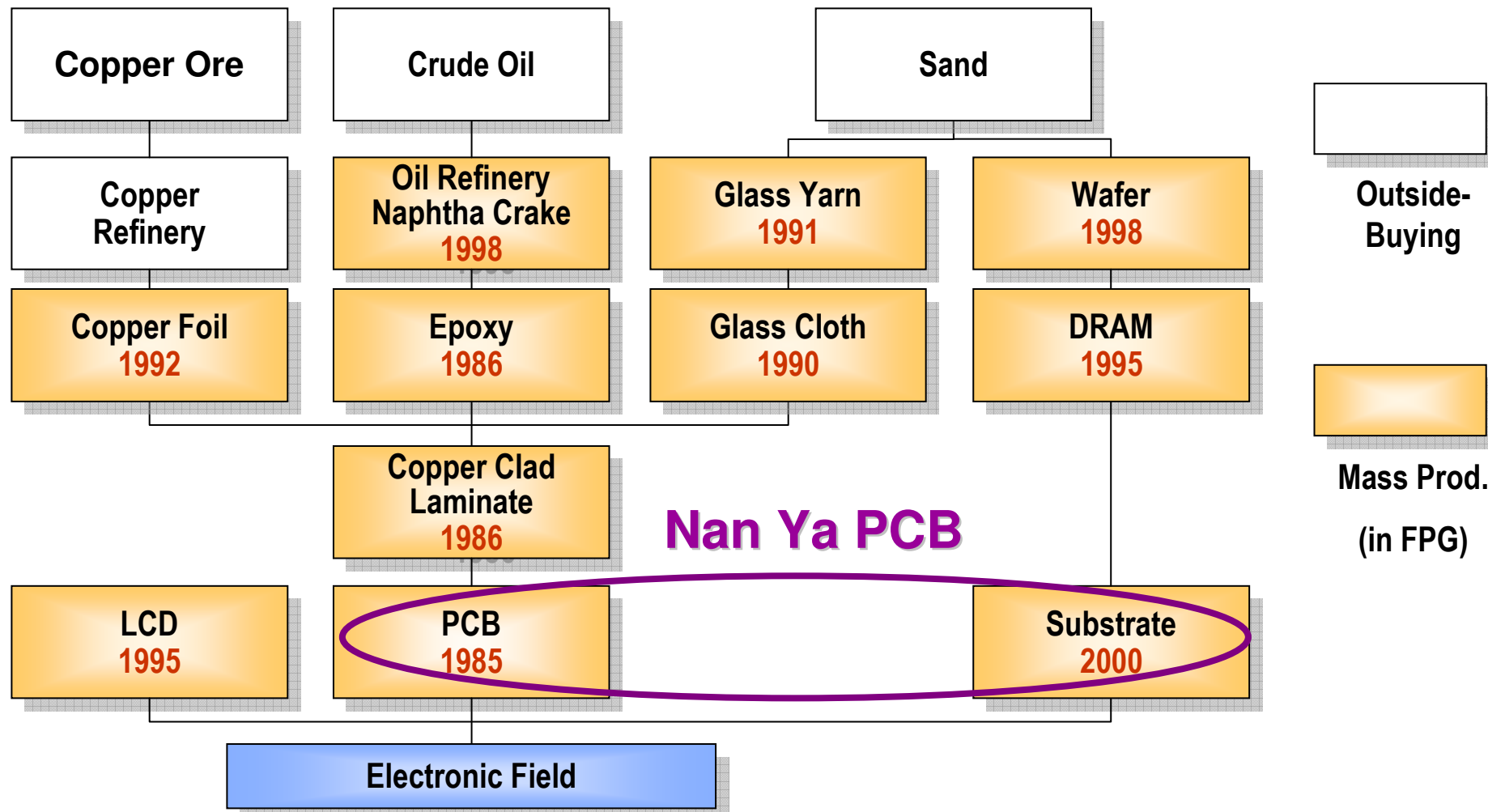


## Safe Harbor Notice

- Nan Ya PCB's statements of its current expectations are forward-looking statements subject to significant risks and uncertainties and actual results may differ materially from those contained in the forward-looking statements.
- Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.



# Vertical Integration within FPG





## Milestone

Year 1985	Start up PCB mass production
Year 1997	Establish Na Ya PCB Corporation
Year 2000	Start up Wire-bond Substrate mass production
Year 2001	Start up Flip-chip Substrate mass production
Year 2002	Start up Kunshan PCB mass production
Year 2006	IPO (TWSE Ticker No.: 8046)



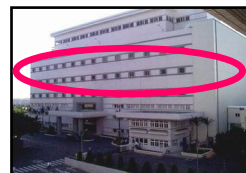
# Production Allocation and Monthly Capacity



Flip Chip



P1+P5 15M Units



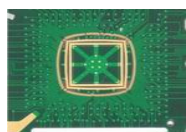
P6 8M Units



P7 7M Units



P8 (15M Units)



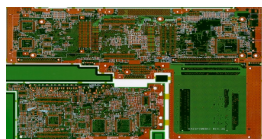
Wire Bond



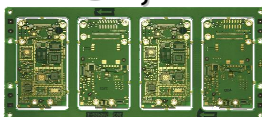
P2 320KSF



KS P2 225KSF



PCB, HDI



P3 160KSF



KS P1 1.2MSF



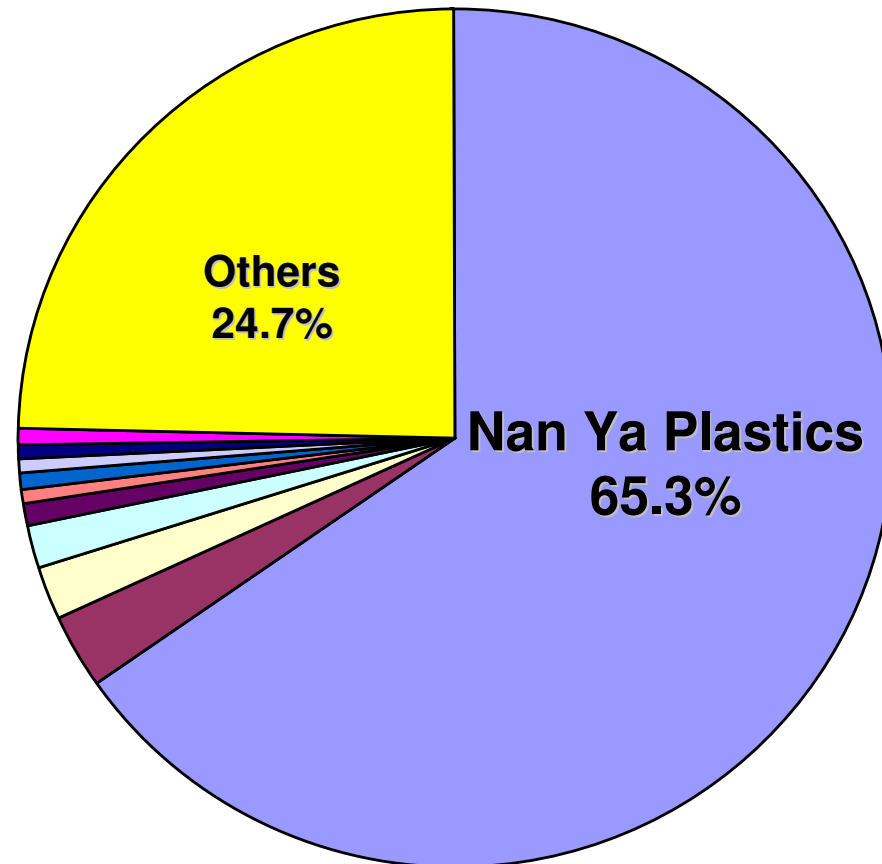
KS P2 600KSF

**Note: KS=Kunshan China manufacturing campus**



# Structure of Shareholders

ABP	0.5%
GIC	0.5%
Fidelity Greater China Fund	0.5%
Capital High Tech Fund	0.6%
Shin Kong Life Insurance	0.7%
Standard Chartered Emerging Market	0.7%
Citi Asia Fund	1.9%
Nan Shan Life Insurance	1.9%
Chunghwa Post	2.7%

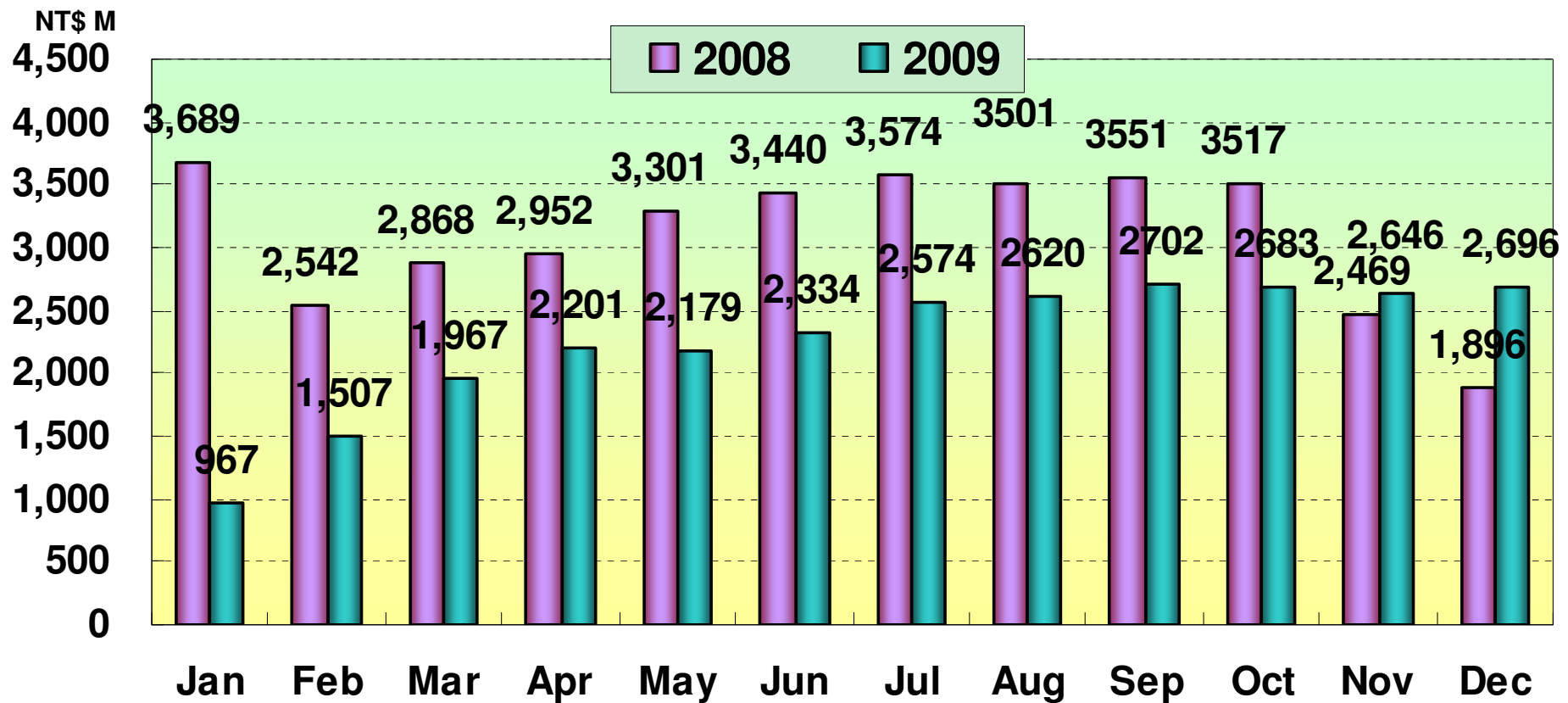


**Total Shares: 630,398,531 shares**

**Date: August, 2009**



## 2008~2009 Monthly Revenue in Taiwan



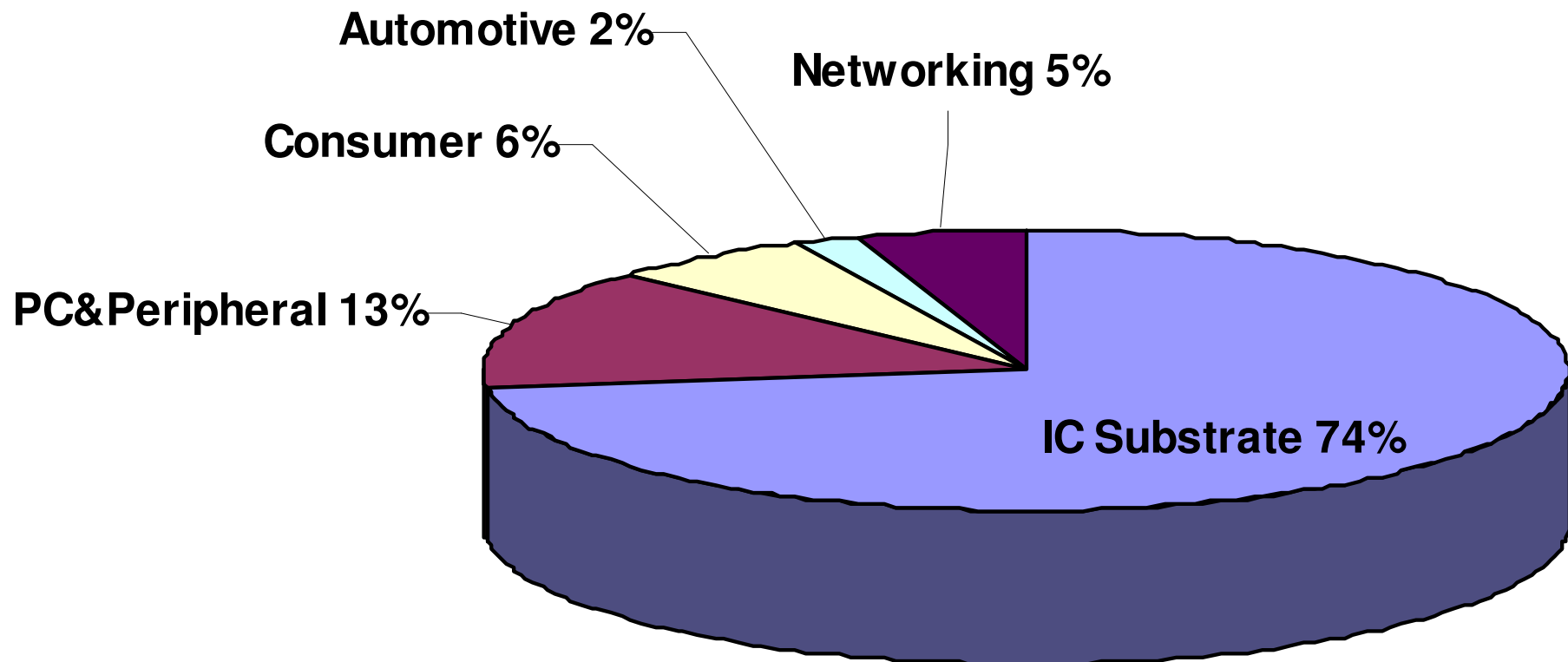
➤ 2009 December Sales = NT\$ 2.7 Billion ; MoM=+1.9% ; YoY=+42.2%

➤ Accumulated 2009 Sales = NT\$ 27.08 Billion ; YoY=-27.4%





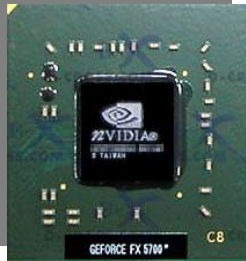
# 2009 Sales Breakdown by Application







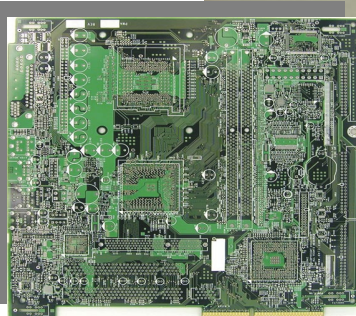
# Products & Applications-PC



**GPU  
FC-BGA**



**CPU  
FC-PGA**



**Conventional PCB  
PC Motherboard**



**South Bridge  
WB-BGA**



**DDR II DRAM Module**



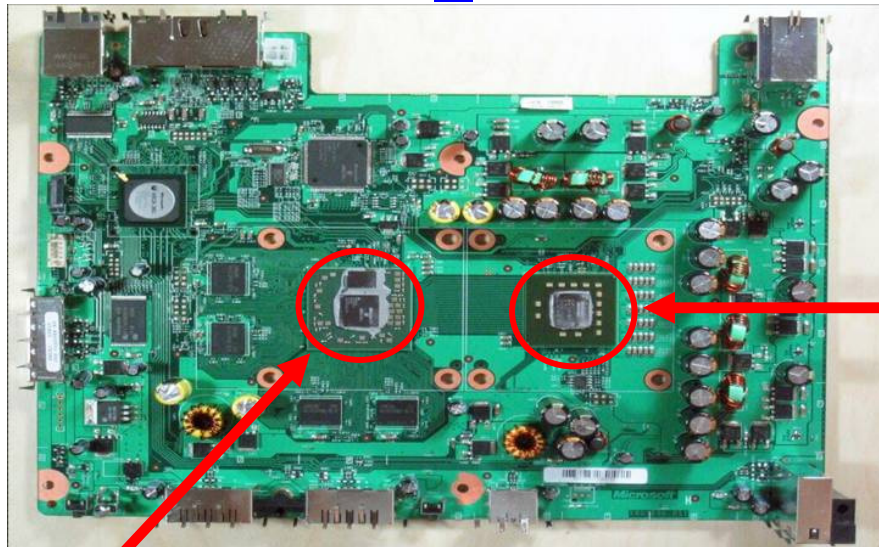
**North Bridge  
FC-BGA**





# Products & Applications-Game Console

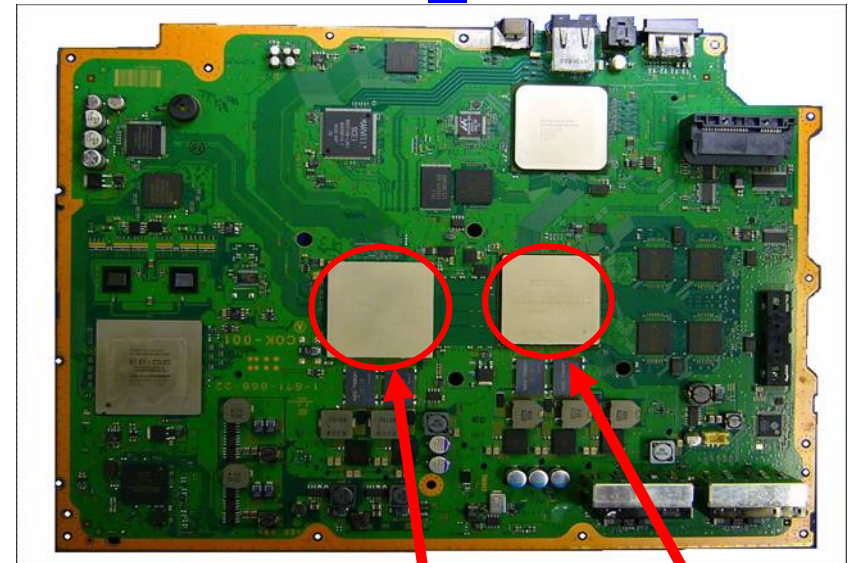
A



MPU  
FC-BGA  
27mm<sup>2</sup>  
2/2/2

Integrated Chipset  
FC-BGA  
35mm<sup>2</sup>  
3/2/3

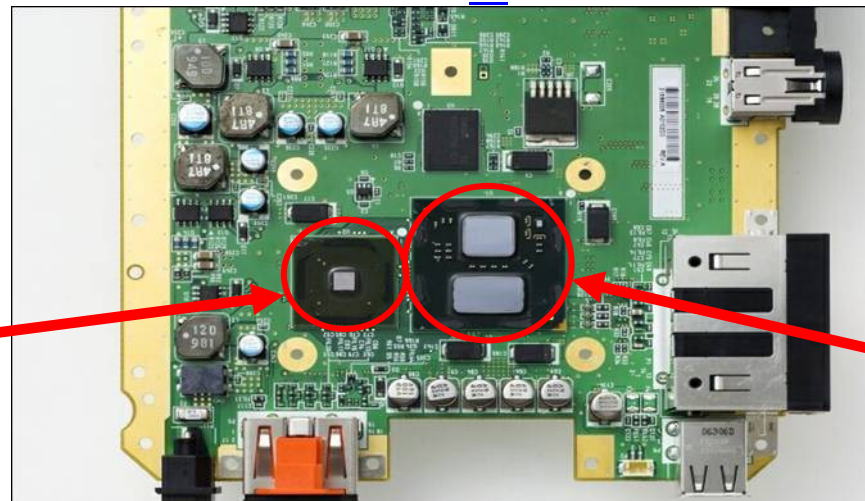
B



Integrated Chipset  
FC-BGA  
42.5mm<sup>2</sup>  
3/2/3

MPU  
FC-BGA  
33mm<sup>2</sup>  
2/2/2

C

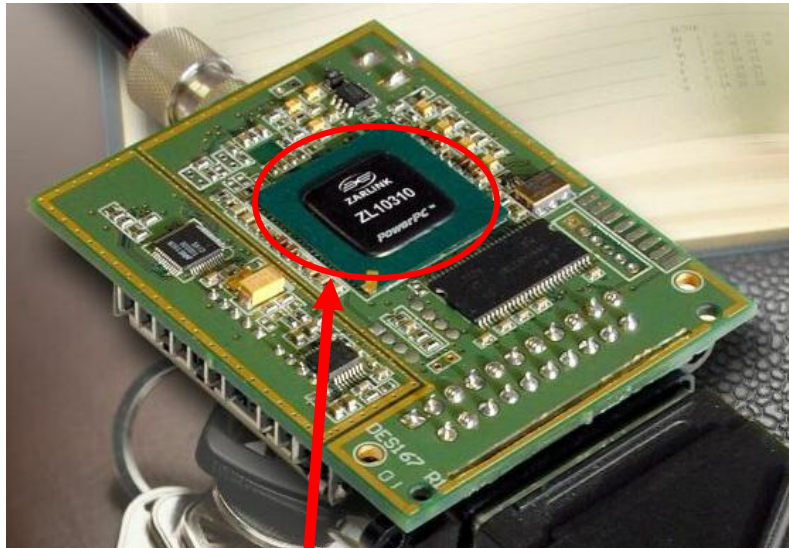


MPU  
FC-BGA  
21mm<sup>2</sup>  
2/2/2

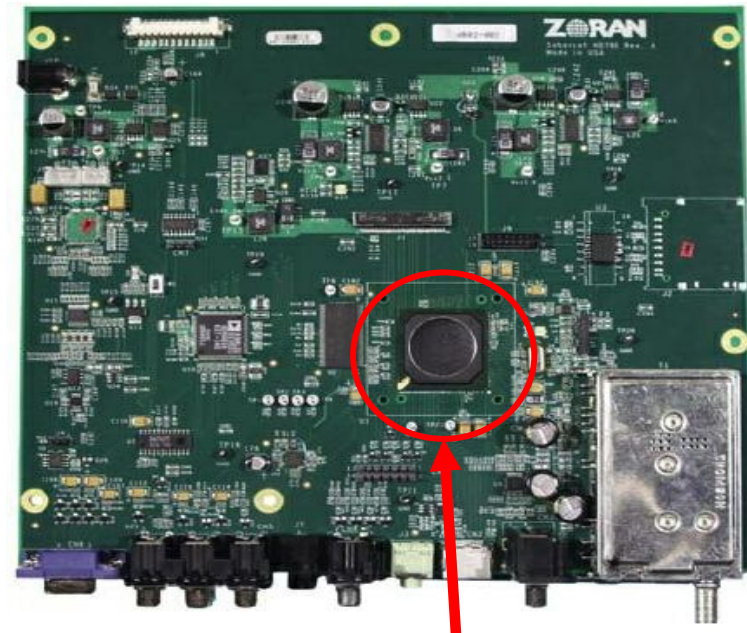
Integrated Chipset  
FC-BGA  
31mm<sup>2</sup>  
2/2/2



# Products & Applications-Others

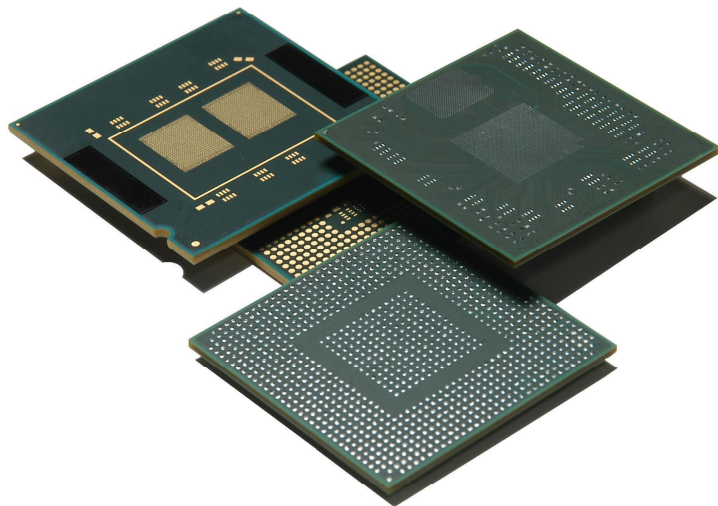


Set-Top Box  
37.5mm<sup>2</sup>  
2/2/2



HDTV Chipset  
35mm<sup>2</sup>  
2/2/2

- Set-Top Box and HDTV started to migrate to flip-chip design in 2007, and annual demand has been expected to increase dramatically in 2009 .



# Thank You

## Q & A





# FC Substrate Development Trend

## ➤ CPU Development

